Qualcomm

RF360
Europe GmbH

Data sheet

SAW duplexer

LTE / 5G band 1

Part number:	B1255
Ordering code:	B39212B1255L210
Date:	November 23, 2020
Version:	2.4

DCN: 80-PA243-350 Rev. E

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1 Application

- Duplexer for 4G and 5G band 1
- LTE band 1 uplink: 1950 MHz (pass band 60 MHz)
- LTE band 1 downlink: 2140 MHz (pass band 60 MHz)
- Low-loss SAW duplexer for mobile telephone LTE Band 1 systems, also suitable for CDMA applications
- Qualcomm® micro-Acoustic Power Management (MAPM)
- Low insertion attenuation
- Low amplitude ripple

2 Features

- Package size $1.6_{\pm 0.05}$ mm × $1.2_{\pm 0.05}$ mm
- Package height 0.6 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

3 Package

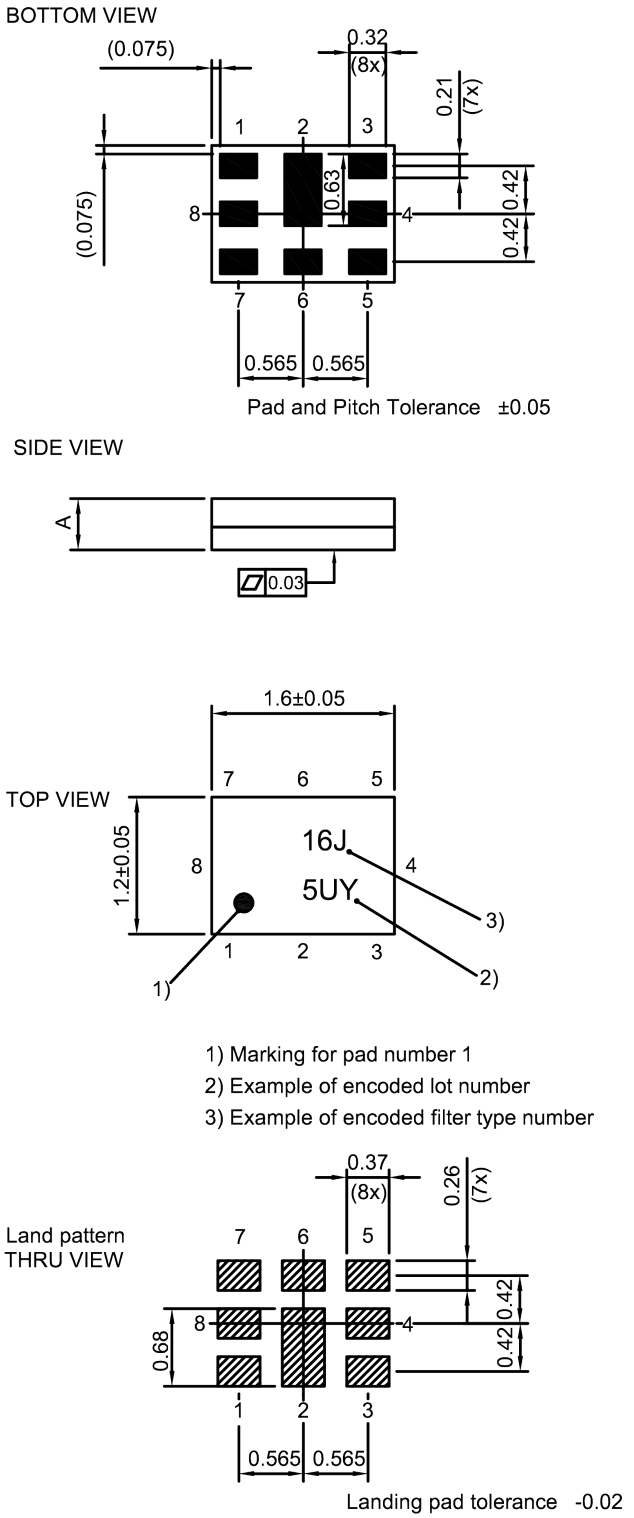

Figure 1: Drawing of package with package height A = 0.6 mm (max.). See Sec. Package information (p. 23).

4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 8 Ground

5 Matching circuit

- L_{p1} = 24 nH
- L_{p3} = 16 nH
- L_{p6} = 3.0 nH

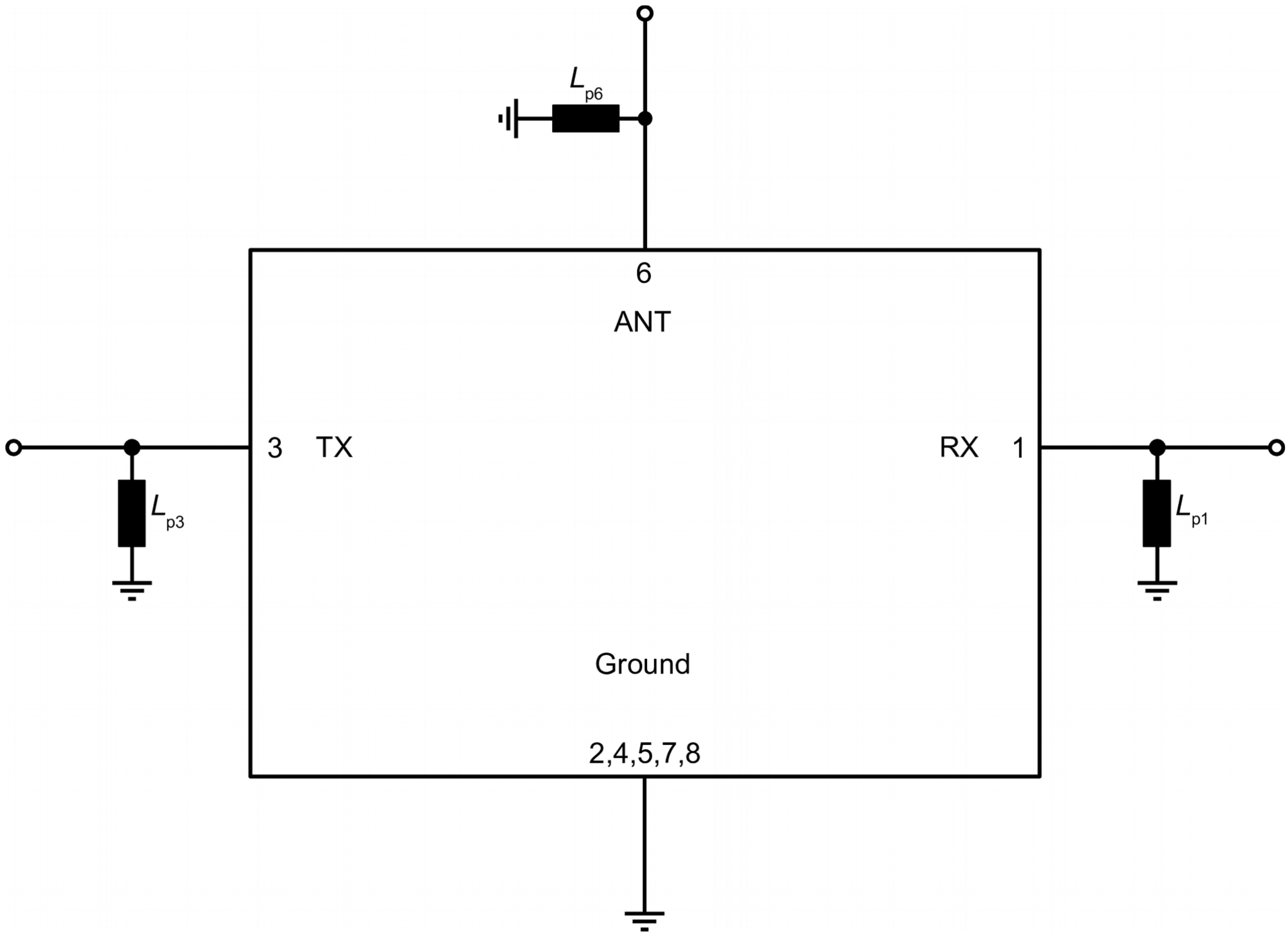

Figure 2: Schematic of matching circuit.

External shunt inductor for ESD protection is recommended at any ports towards antenna.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= −30 °C ... +90 °C
TX terminating impedance	Z_{TX}	= 50 Ω // 16 nH[1)]
ANT terminating impedance	Z_{ANT}	= 50 Ω // 3.0 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω // 24 nH[1)]

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	1950	—	MHz
Maximum insertion attenuation							
	1920 ... 1980	MHz	$\alpha_{INT,max}$ 2)	—	0.9	1.8	dB
	1920.25 ... 1979.75	MHz	α_{max}	—	1.2	1.8	dB
Amplitude ripple (p-p)							
	1920.25 ... 1979.75	MHz	$\Delta\alpha$ 3)	—	0.2	1.0	dB
	1920.25 ... 1979.75	MHz	$\Delta\alpha$ 4)	—	0.5	1.5	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	1920.25 ... 1979.75	MHz		—	1.4	2.0	
@ ANT port	1920.25 ... 1979.75	MHz		—	1.4	2.0	
Minimum attenuation			α_{min}				
	10 ... 1574	MHz		30	40	—	dB
	814 ... 849	MHz		39	45	—	dB
	859 ... 894	MHz		39	44	—	dB
	880 ... 915	MHz		39	44	—	dB
	925 ... 960	MHz		39	43	—	dB
	1166 ... 1187	MHz		35	40	—	dB
	1226 ... 1250	MHz		35	40	—	dB
	1427.9 ... 1462.9	MHz		35	40	—	dB
	1452 ... 1496	MHz		35	41	—	dB
	1475.9 ... 1510.9	MHz		35	41	—	dB
	1559 ... 1563	MHz		40	43	—	dB
	1565.42 ... 1573.374	MHz		40	44	—	dB
	1573.374 ... 1577.466	MHz		40	44	—	dB
	1577.466 ... 1585.42	MHz		40	44	—	dB
	1597.551 ... 1605.886	MHz		40	45	—	dB
	1710 ... 1785	MHz		30	37	—	dB
	1805 ... 1865	MHz		20	32	—	dB
	1865 ... 1880	MHz		10	28	—	dB
	2010 ... 2025	MHz		8[5)]	11	—	dB
	2110.25 ... 2169.75	MHz		44	47	—	dB
	2300 ... 2400	MHz		27	38	—	dB
	2400 ... 2500	MHz		27	35	—	dB
	2496 ... 2690	MHz		27	31	—	dB

Characteristics TX – ANT			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
	2500 ... 2690	MHz	27	31	—	dB
	3300 ... 3800	MHz	18	23	—	dB
	3300 ... 4200	MHz	18	23	—	dB
	3840 ... 3960	MHz	18	23	—	dB
	4400 ... 5000	MHz	12	17	—	dB
	4900 ... 5950	MHz	8	13	—	dB
	5760 ... 5940	MHz	8	13	—	dB

1) See Sec. Matching circuit (p. 6).
2) Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
3) Over any 5 MHz.
4) Over any 20 MHz.
5) Valid for temperature T = +15 °C...+90 °C.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= −30 °C ... +90 °C
TX terminating impedance	Z_{TX}	= 50 Ω // 16 nH[1]
ANT terminating impedance	Z_{ANT}	= 50 Ω // 3.0 nH[1]
RX terminating impedance	Z_{RX}	= 50 Ω // 24 nH[1]

Characteristics ANT – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	2140	—	MHz
Maximum insertion attenuation			α_{max}				
	2110.25 ... 2169.75	MHz		—	1.5	2.3	dB
Amplitude ripple (p-p)							
	2110.25 ... 2169.75	MHz	$\Delta\alpha$[2]	—	0.2	1.1	dB
	2110.25 ... 2169.75	MHz	$\Delta\alpha$[3]	—	0.3	1.5	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	2110.25 ... 2169.75	MHz		—	1.6	2.1	
@ RX port	2110.25 ... 2169.75	MHz		—	1.5	2.2	
Minimum attenuation			α_{min}				
	10 ... 1920	MHz		32	42	—	dB
	703 ... 748	MHz		40	54	—	dB
	824 ... 849	MHz		40	52	—	dB
	832 ... 862	MHz		40	52	—	dB
	880 ... 915	MHz		40	51	—	dB
	1427.9 ... 1462.9	MHz		40	45	—	dB
	1710 ... 1785	MHz		32	44	—	dB
	1920.25 ... 1979.75	MHz		45	53	—	dB
	2010 ... 2050	MHz		26	30	—	dB
	2300 ... 2400	MHz		30	40	—	dB
	2400 ... 2483	MHz		30	40	—	dB
	2496 ... 2690	MHz		30	42	—	dB
	2500 ... 2570	MHz		30	42	—	dB
	3300 ... 3800	MHz		30	49	—	dB
	3300 ... 4200	MHz		30	40	—	dB
	4400 ... 5000	MHz		26	31	—	dB
	4900 ... 5950	MHz		26	31	—	dB

1) See Sec. Matching circuit (p. 6).
2) Over any 5 MHz.
3) Over any 20 MHz.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= −30 °C ... +90 °C
TX terminating impedance	Z_{TX}	= 50 Ω // 16 nH[1)]
ANT terminating impedance	Z_{ANT}	= 50 Ω // 3.0 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω // 24 nH[1)]

Characteristics TX – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Minimum isolation							
	1920.25 ... 1979.75	MHz	α_{min}	55	61	—	dB
	2110 ... 2170	MHz	$\alpha_{INT,min}$ [2)]	55	62	—	dB

[1)] See Sec. Matching circuit (p. 6).
[2)] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

7 Maximum ratings

Storage temperature	T_{STG} [1] = −40 °C ... +90 °C	
DC voltage	$\|V_{DC}\|$ = 5.0 V (max.)	
ESD voltage		
	V_{ESD} [2] = 125 V (max.)	Machine model.
	V_{ESD} [3] = 150 V (max.)	Human body model.
	V_{ESD} [4] = 600 V (max.)	Charged device model.
Input power	P_{IN}	
@ TX port: 1920 ... 1980 MHz	31 dBm	Continuous wave for 5000 h @ 50 °C.
@ TX port: 1920 ... 1980 MHz	31 dBm	5MHz LTE uplink signal 1RB for 5000 h @ 50 °C.
@ TX port: 1920 ... 1980 MHz	30 dBm	5MHz 5G NR (CP-OFDM) 1RB for 5000 h @ 50 °C.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
3) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
4) According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

8 Transmission coefficients

8.1 TX – ANT

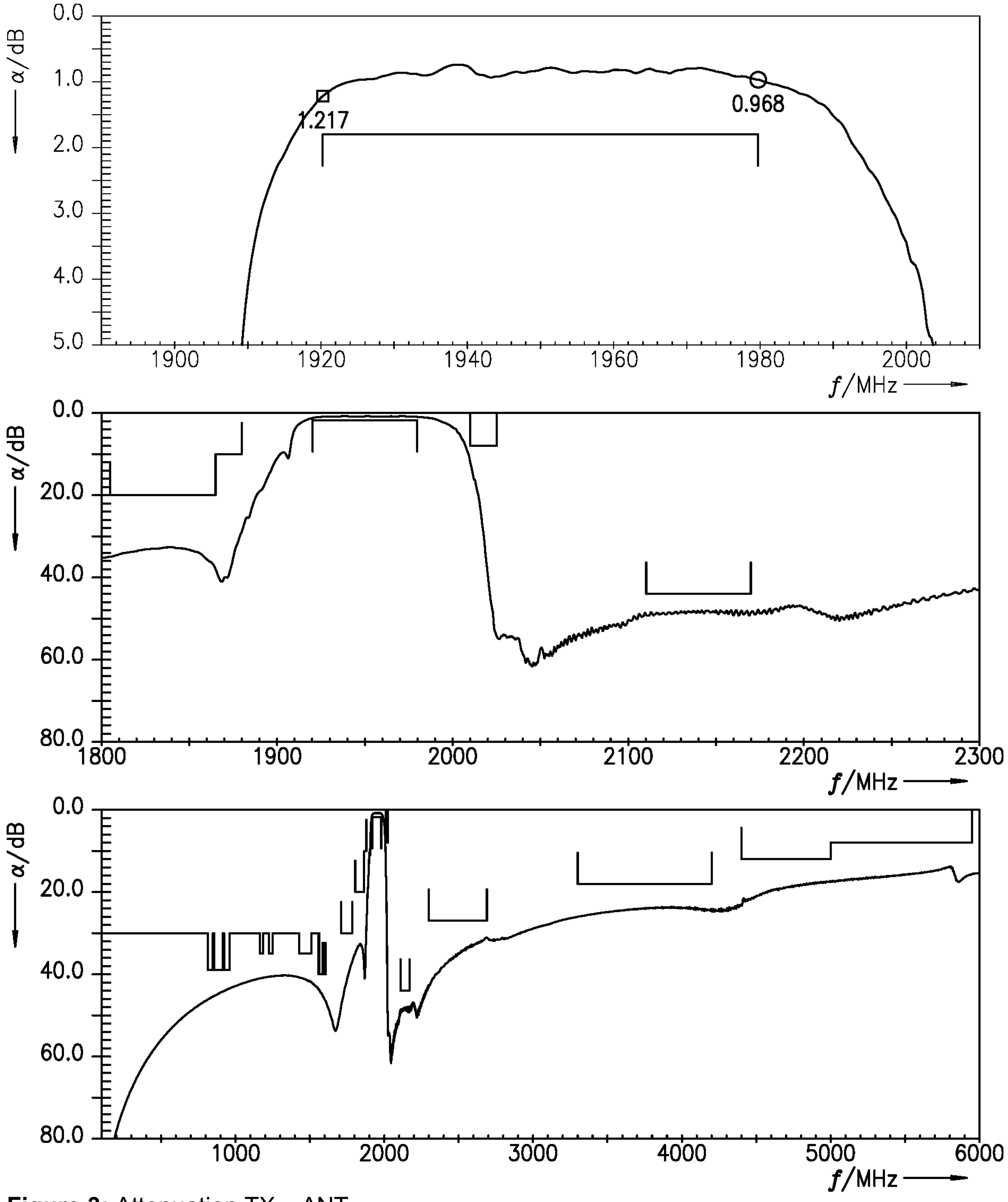

Figure 3: Attenuation TX – ANT.

8.2 ANT – RX

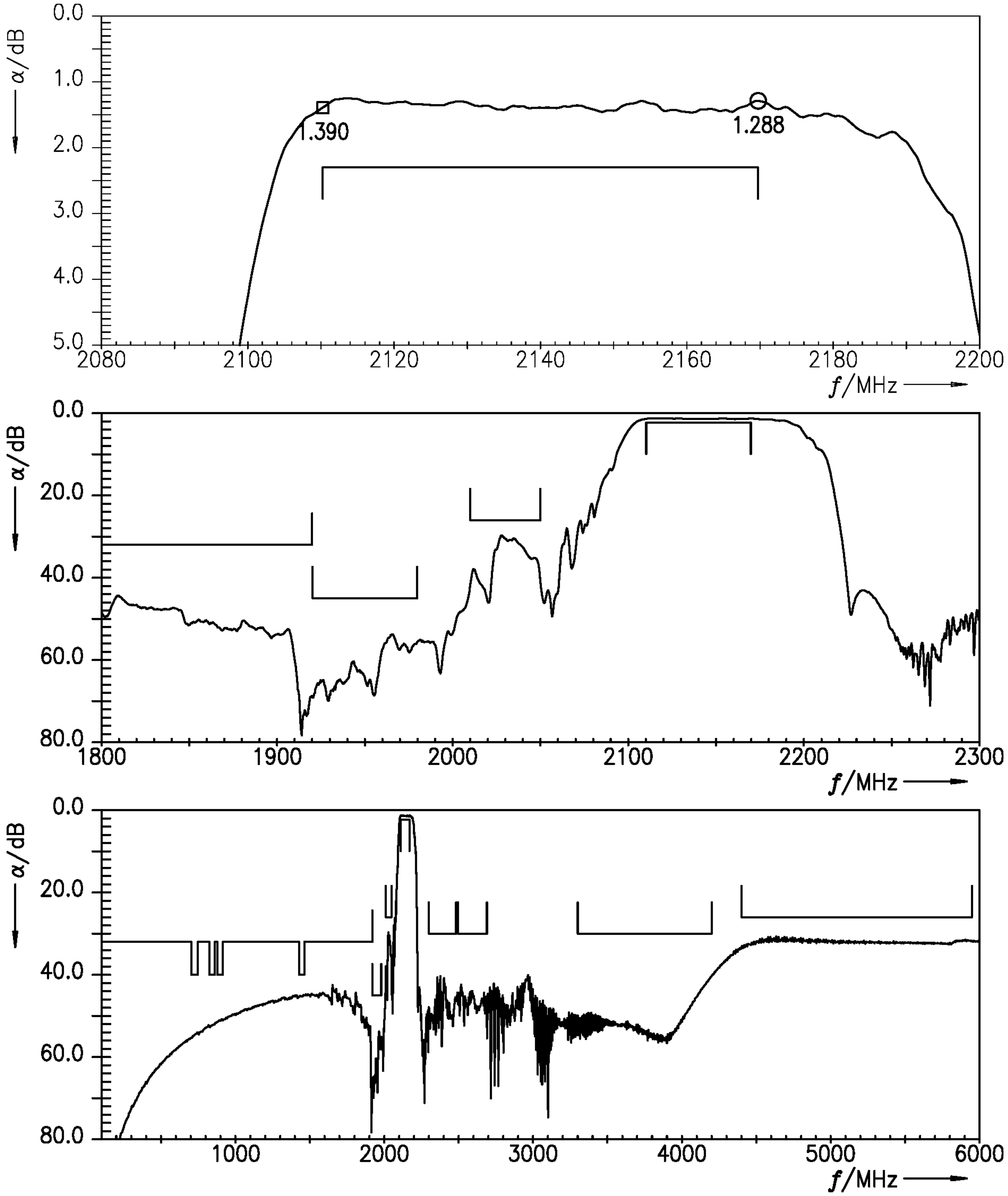

Figure 4: Attenuation ANT – RX.

8.3 TX – RX

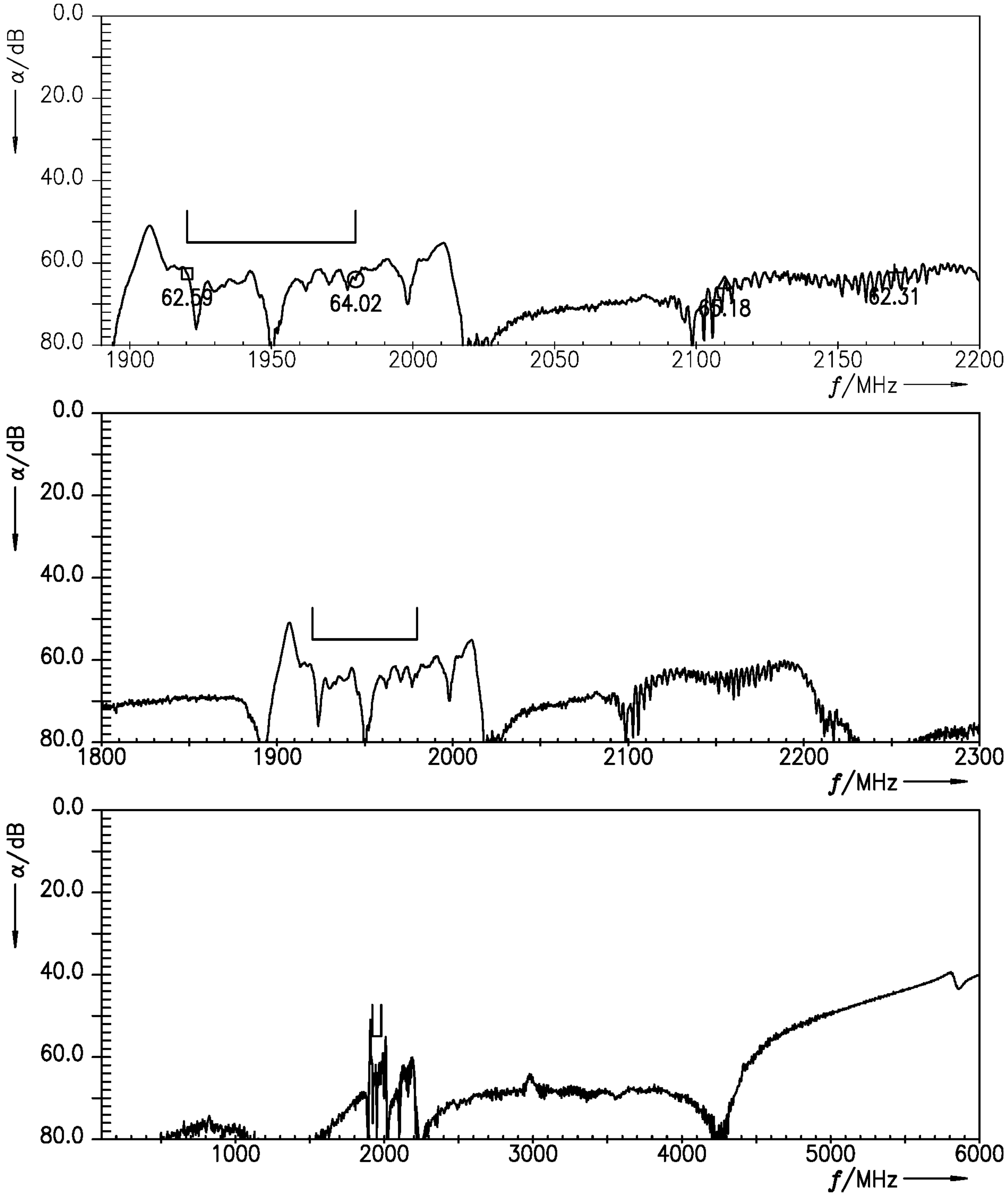

Figure 5: Isolation TX – RX.

9 Reflection coefficients

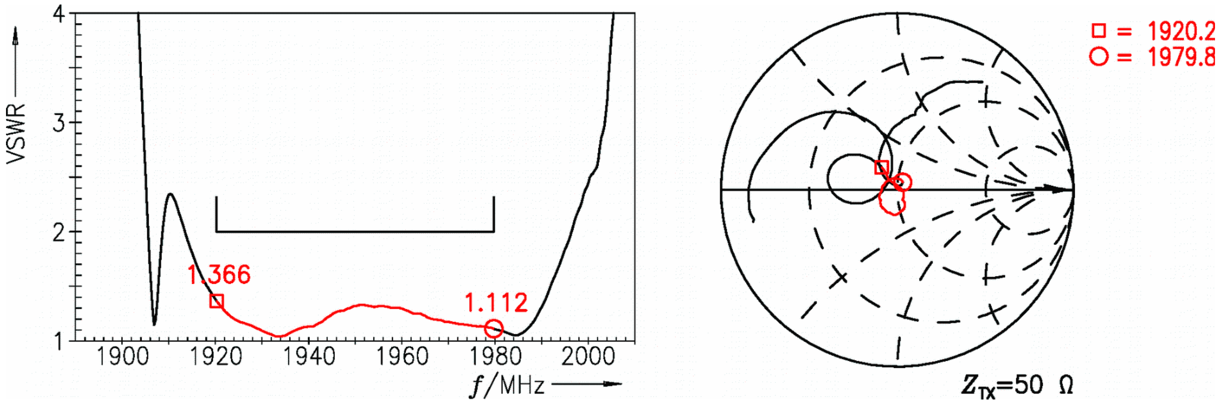

Figure 6: Reflection coefficient at TX port.

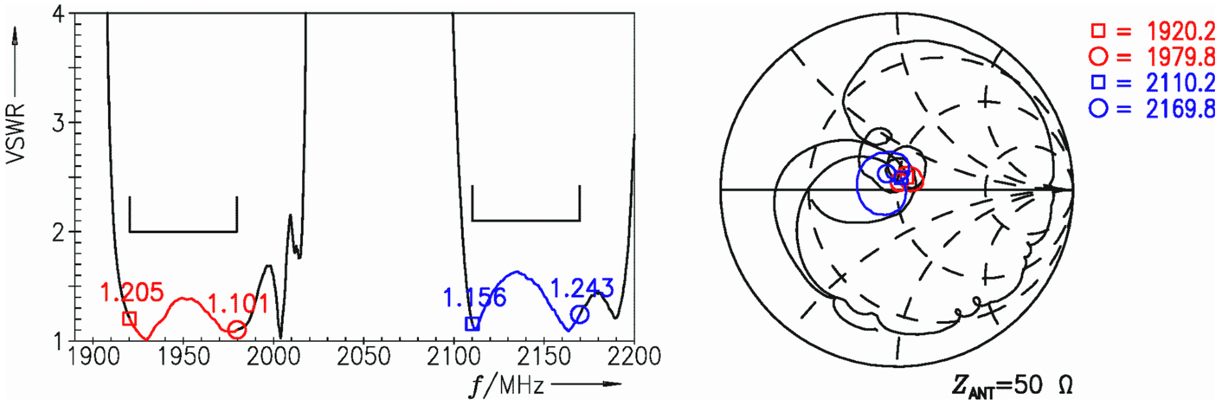

Figure 7: Reflection coefficient at ANT port.

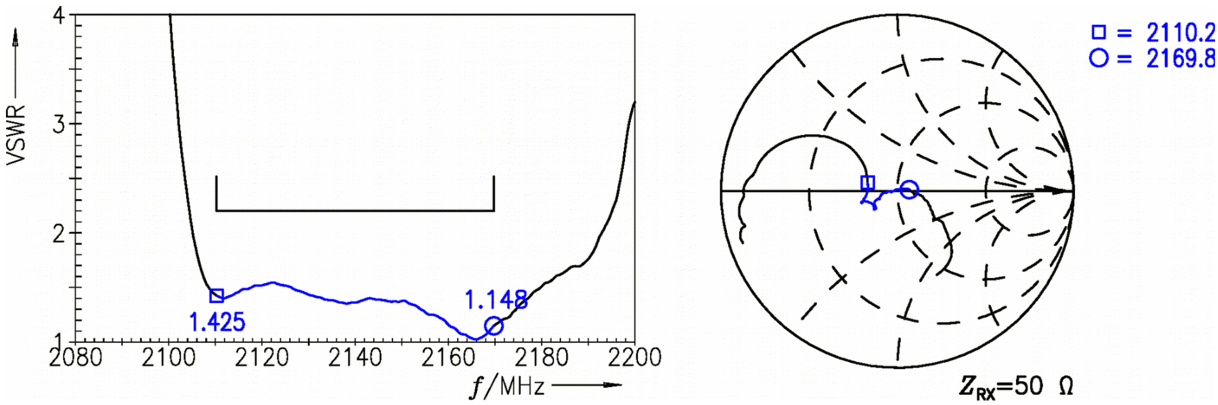

Figure 8: Reflection coefficient at RX port.

10 Packing material

10.1 Tape

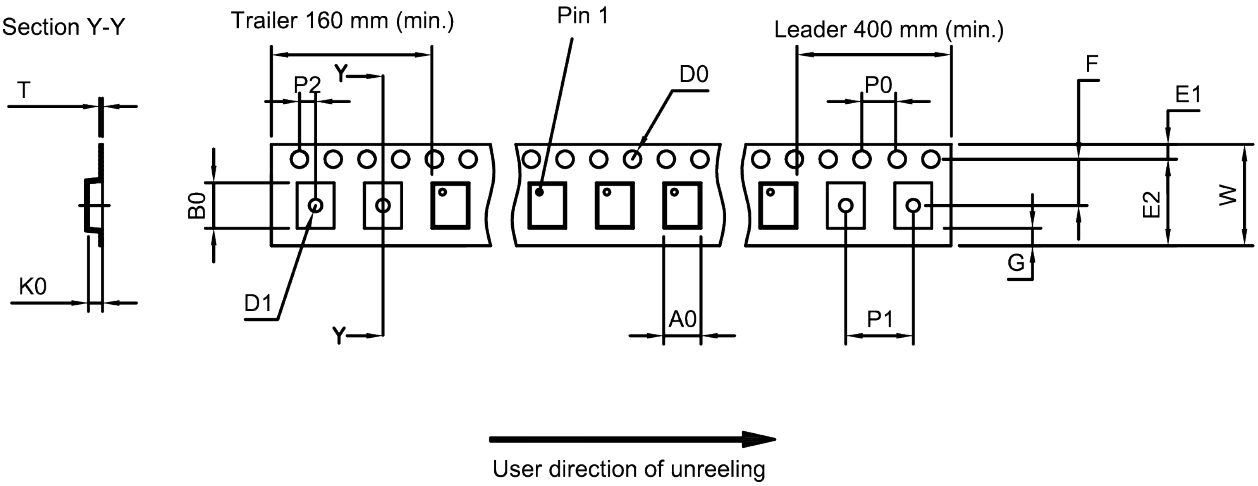

Figure 9: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	$1.5_{\pm 0.05}$ mm	E_2	6.25 mm (min.)	P_1	$4.0_{\pm 0.1}$ mm
B_0	$1.9_{\pm 0.05}$ mm	F	$3.5_{\pm 0.05}$ mm	P_2	$2.0_{\pm 0.05}$ mm
D_0	$1.5_{+0.1/-0}$ mm	G	0.75 mm (min.)	T	$0.25_{\pm 0.03}$ mm
D_1	$0.8_{+0.1/-0}$ mm	K_0	$0.63_{\pm 0.05}$ mm	W	$8.0_{+0.3/-0.1}$ mm
E_1	$1.75_{\pm 0.1}$ mm	P_0	$4.0_{\pm 0.1}$ mm		

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

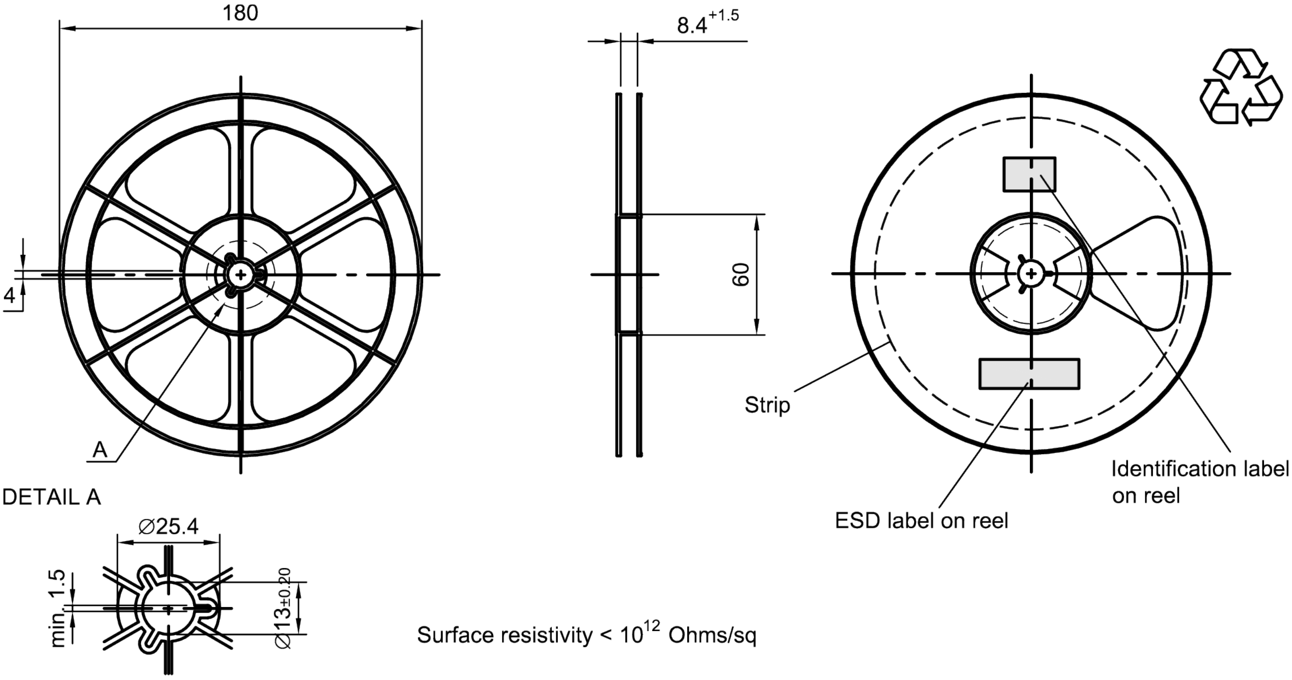

Figure 10: Drawing of reel (first-angle projection) with diameter of 180 mm.

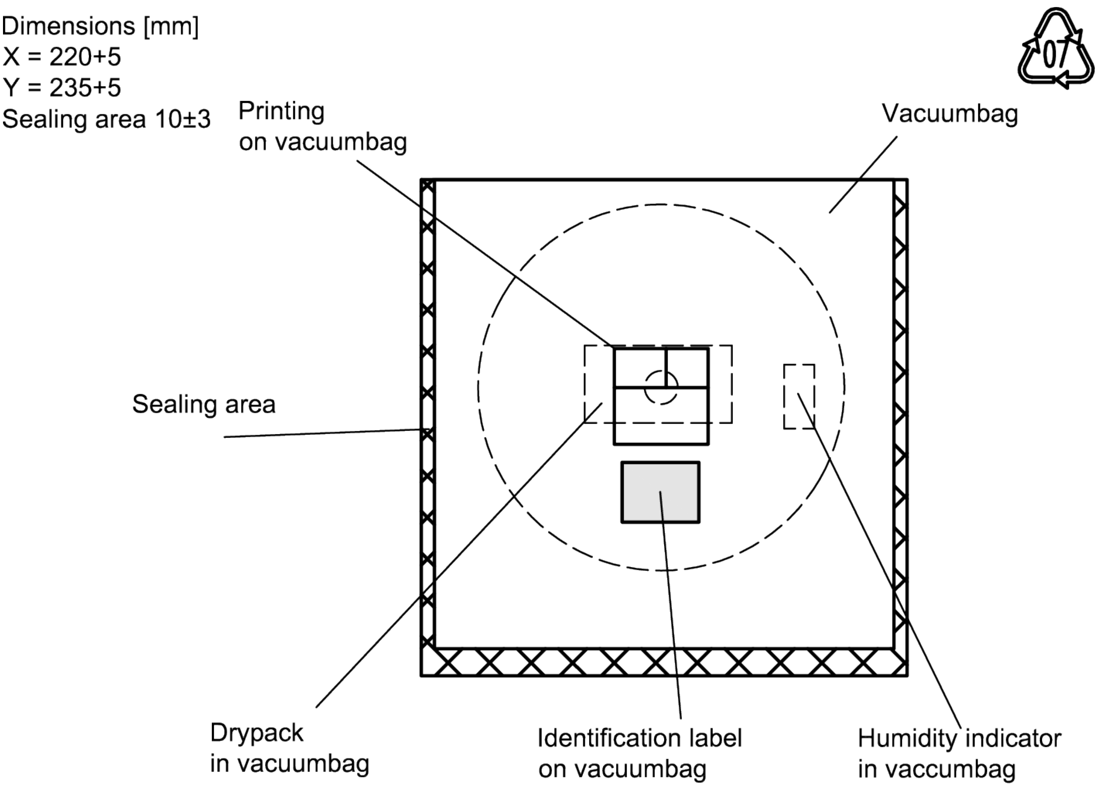

Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

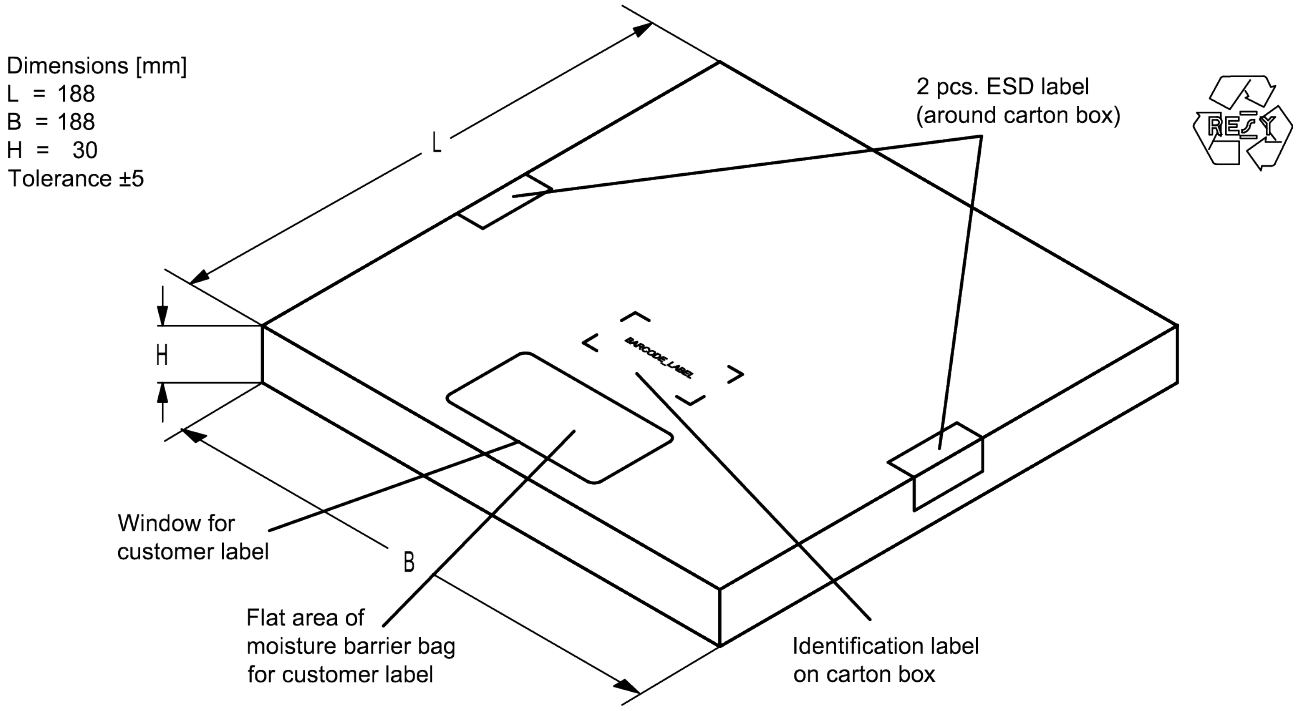

Figure 12: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

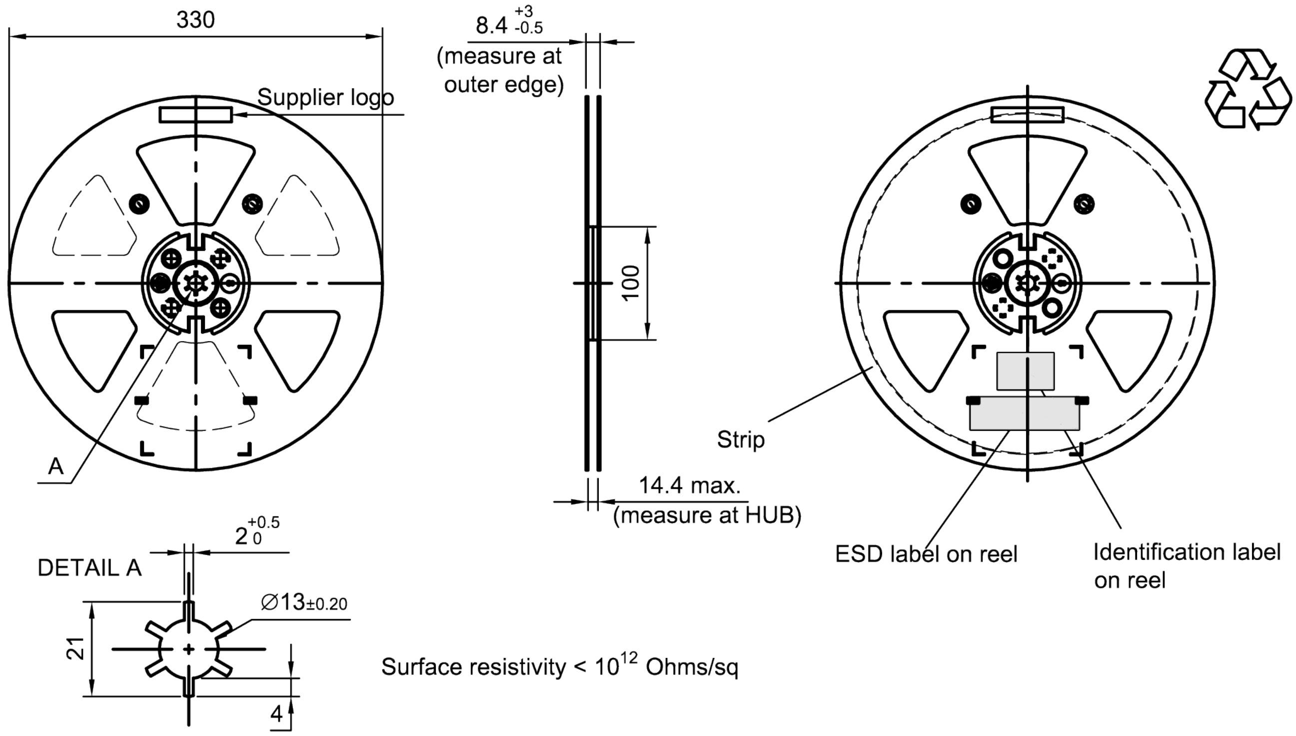

Figure 13: Drawing of reel (first-angle projection) with diameter of 330 mm.

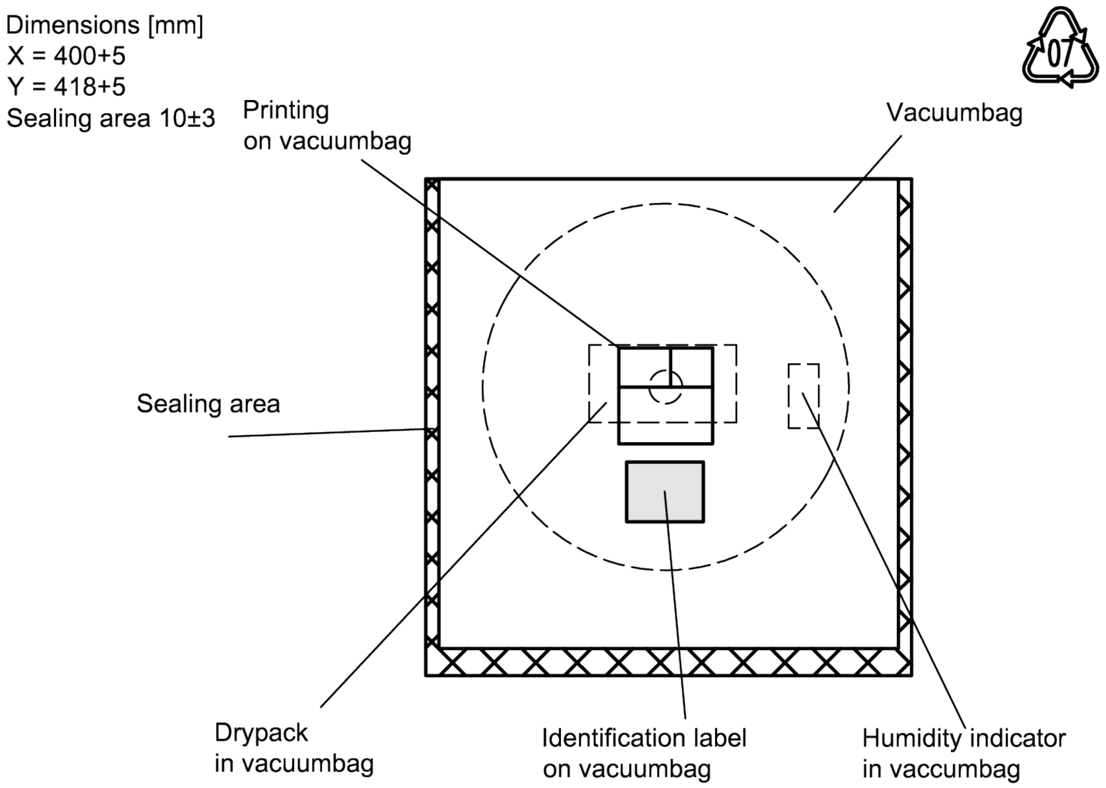

Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

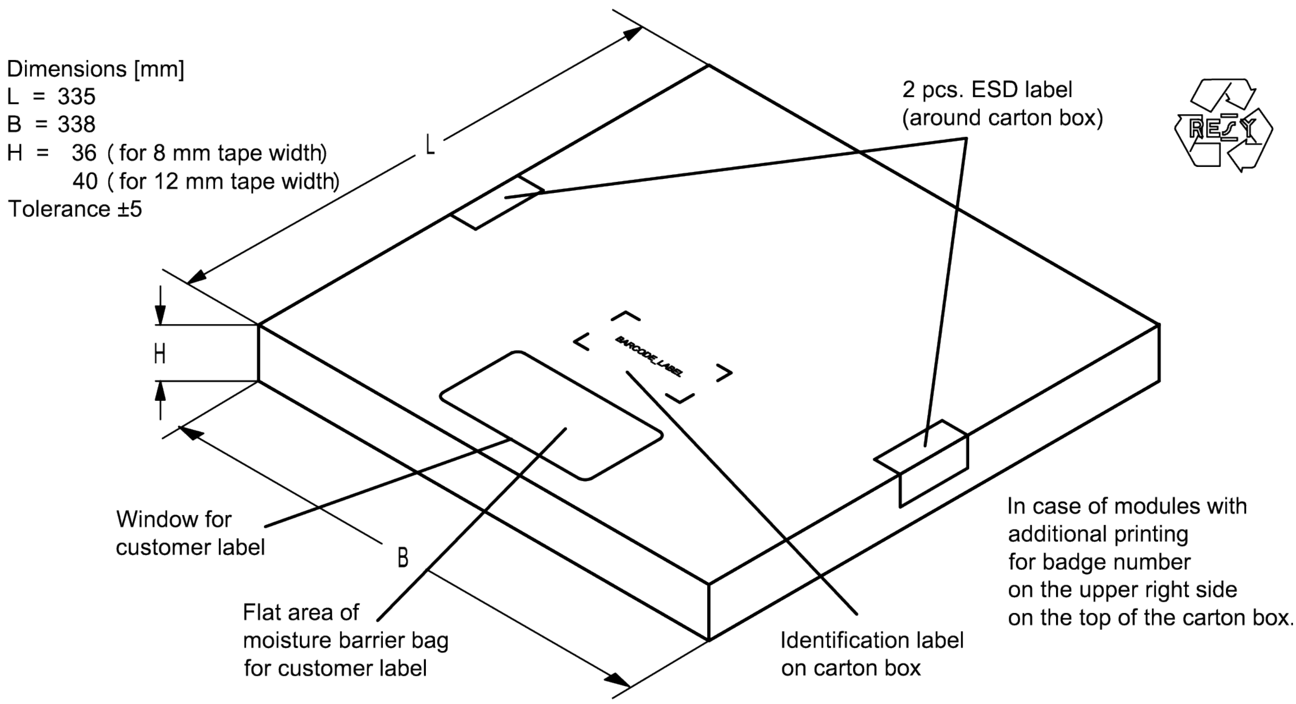

Figure 15: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

  The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
  is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.

  16J => **1234**

  $\mathbf{1} \times 32^2 + \mathbf{6} \times 32^1 + \mathbf{18\ (=J)} \times 32^0$ = **1234**

  The BASE32 code for product type B1255 is 177.

- Lot number:

  The last 5 digits of the lot number, e.g., **12345**,
  are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.

  5UY => **12345**

  $\mathbf{5} \times 47^2 + \mathbf{27\ (=U)} \times 47^1 + \mathbf{31\ (=Y)} \times 47^0$ = **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature *T*	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

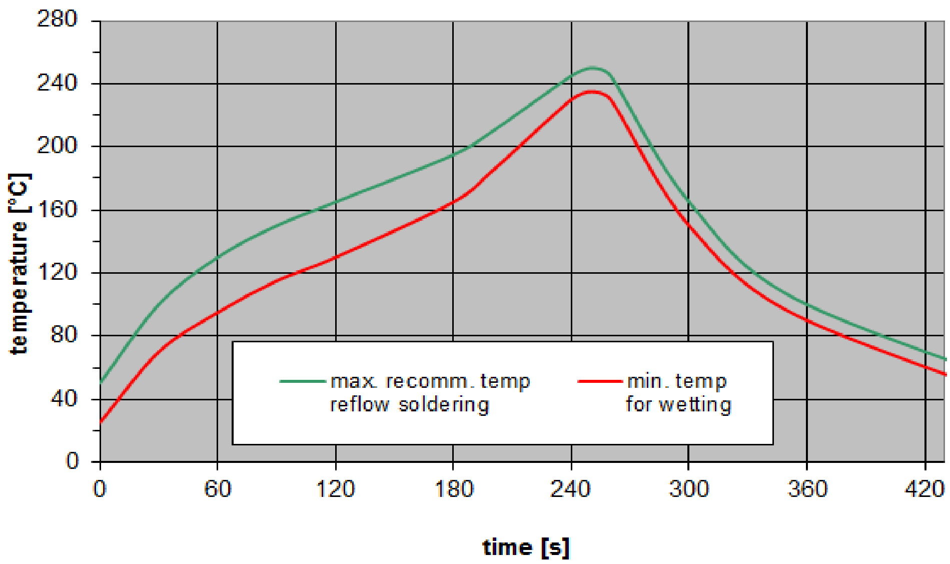

Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Ordering codes and packing units

Ordering code	Packing unit
B39212B1255L210S 5	5000 pcs
B39212B1255L210W 5	5000 pcs

Table 4: Ordering codes and packing units.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.qualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (https://rffe.qualcomm.com). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
   The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

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